

# Power and area efficient MOSFET-C filter for very low frequency applications

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**Abstract** New circuit design techniques for implementing very high-valued resistors are presented, significantly improving power and area efficiency of analog front-end signal processing in ultra-low power biomedical systems. Ranging in value from few hundreds of  $M\Omega$  to few hundreds of  $G\Omega$ , the proposed floating resistors occupy a very small area, and produce accurately tunable characteristics. Using this approach, a low-pass MOSFET-C filter with tunable cutoff frequency ( $f_C = 20 \text{ Hz}–184 \text{ kHz}$ ) has been implemented in a conventional  $0.18 \mu\text{m}$  CMOS technology. Occupying  $0.045 \text{ mm}^2/\text{pole}$ , the power consumption of this filter is  $540 \text{ pW/Hz/pole}$  with a measured IMFDR of 70 dB.

**Keywords** CMOS integrated circuits · Continuous-time filter · High-valued resistance · Low-power · MOSFET-C filter · Programmable filter · Subthreshold · Weak inversion · Widely tunable circuits

## 1 Introduction

Analog front-end data acquisition and signal processing are critically important functions in modern biomedical systems, such as in biopotential capture and neural recording

[1–4]. Figure 1 depicts a conceptual data acquisition chain for biomedical systems. Based on this topology, the biomedical signals are converted to electrical signals by parallel transducers; the electrical signals are then amplified by a low-noise amplifier. The next step will be to convert the analog signals to digital signals (analog-to-digital converter) after filtering to be further analyzed by the digital signal processors. Performance parameters such as linearity, gain and noise, as well as system specifications such as power dissipation and silicon area, are the main issues in design of analog front-end for this type of applications. Because of very limited energy budget in such battery operated or battery less systems [5], extremely power efficient circuit design techniques must be employed.

Depending on application, the bandwidth of input signal ranges from below 1 Hz to few kHz [6]. For example, signal bandwidth for Electroencephalography (EEG), Electrooculography (EOG), and Electrocardiography (ECG) applications are in the range of 0.5–40 Hz, DC to 10 Hz, and 0.05–100 Hz, respectively. Therefore, versatile amplification and filtering front-end circuits with very low operating frequencies are very desirable.

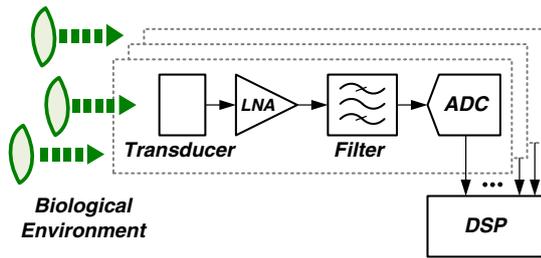
In [1], capacitance and transconductance scaling techniques have been introduced to implement a low-pass 2.4 Hz filter with  $690 \text{ nW/Hz/pole}$  power dissipation and  $0.16 \text{ mm}^2/\text{pole}$  area in  $1 \mu\text{m}$  CMOS. To generate a very large time constant, transconductance-transimpedance technique has been used in [2]. An integrator with a time constant of 0.2–10 s has been implemented in  $0.8 \mu\text{m}$  CMOS, consuming 230 nW and occupying  $0.1 \text{ mm}^2$ . To implement low bandwidth amplification stages, a very high-valued pseudo-resistor has been introduced in [3]. In this pseudo-resistor topology, each transistor which occupies  $16 \mu\text{m}^2$ , is biased in weak inversion to exhibit a very high resistivity. While highly nonlinear, it shows a

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**Fig. 1** A conceptual biomedical data acquisition system

resistivity of as high as  $\approx 10^{12} \Omega$ . To reach to the same range of resistivity, in [6] a pseudoresistance combined of NMOS and PMOS devices with better linearity performance has been suggested.

As can be seen, very high resistivity devices are critical components for implementing power and area efficient filters at very low frequencies. In this article some techniques for implementing very high-valued resistors (HVRs) will be presented and used to realize a low frequency MOSFET-C filter [7, 8]. Having a cutoff frequency of as low as 20 Hz, the proposed low-pass filter consumes only 540 pW/Hz/pole and occupies 0.045 mm<sup>2</sup>/pole in 0.18  $\mu\text{m}$  CMOS.

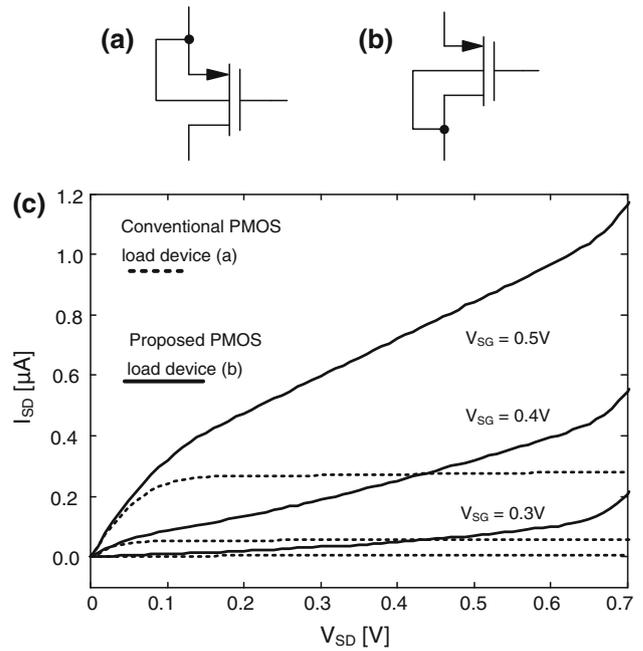
## 2 High-valued resistance

One of the main concerns in the design of very low frequency circuits is the size of passive components [9]. Large passive components can be very expensive in terms of silicon area. Meanwhile, when the size of a component increases, the parasitic elements associated with this device can affect the circuit performance. Therefore, compact and high-valued resistors are very desirable for implementing low-frequency filters. This Section explains step-by-step the topology of the proposed HVRs.

### 2.1 Basic HVR with extended swing

Triode MOS devices have been widely used in design of MOSFET-C filters [10] (Fig. 2(a)). However, the resistivity of such devices is generally limited to few tens of  $\text{M}\Omega$  with a reasonable area occupation. To implement compact and high-valued resistors especially for biomedical applications, several techniques have been proposed in literature [3, 6, 11–14]. The technique that will be discussed here is based on a simple topology first used to implement logic circuits [15]. Using this technique, resistors with values as high as 20  $\text{G}\Omega$  based on small size devices have been fabricated and tested [7].

Previously, it has been demonstrated by the authors that connecting the bulk of a PMOS transistor to its drain will extend the resistivity range of device compared to the



**Fig. 2** High-valued resistance for implementing subthreshold source-coupled logic [15]

conventional bulk-source connected configuration (Fig. 2(b)) [7]. As shown in Fig. 2(c), while the  $I/V$  characteristic of the conventional topology saturates for  $V_{SD}$  values larger than few  $U_T$  ( $U_T$  is the thermodynamic voltage), with the modified topology the resistivity range extends to few hundreds of mV. Ignoring the current of the forward bulk-source PN junction, the equivalent resistance of this topology can be calculated by

$$R_{SD} = \left( \frac{\partial I_{SD}}{\partial V_{SD}} \right)^{-1} = \frac{n_p U_T}{I_{SD}} \times \left( \frac{e^{V_{SD}/U_T} - 1}{(n_p - 1)e^{V_{SD}/U_T} + 1} \right) \quad (1)$$

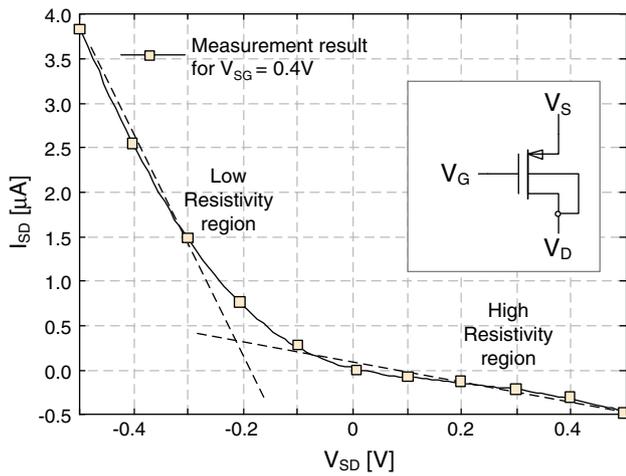
which is obviously very non-linear (here,  $n_p$  is the subthreshold slope factor of the PMOS device). However it can be shown that as long as the device is in subthreshold regime, the linearity remains fairly independent to the absolute value of resistance. Using Taylor expansion for (1):

$$R_{SD} = R_0 \cdot e^{-\frac{V_{SD}}{U_T} \cdot \frac{n_p - 1}{n_p}} \approx R_0 \cdot \left( 1 - \alpha \cdot \frac{V_{SD}}{U_T} + \frac{\alpha}{2} \cdot \left( \frac{V_{SD}}{U_T} \right)^2 \right) \quad (2)$$

where:

$$\alpha = \frac{n_p}{n_p - 1} \quad (3)$$

indicates that the nonlinear part of the  $I/V$  characteristics depends only on  $V_{SD}/U_T$ , and hence the nonlinear component remains the same for different values of bias current or



**Fig. 3** Measured I/V characteristics of the device shown in Fig. 2(b) for positive and negative  $V_{SD}$

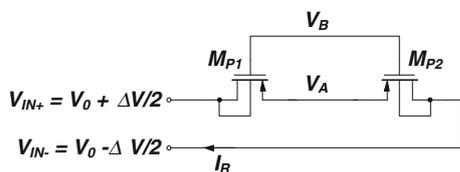
$V_{SG}$ . Here,  $R_0$  stands for the resistivity of the circuit when  $V_{SD} = 0$  V. Based on (2), nonlinearity depends weakly on the biasing condition only through  $n_p$ .

The other important aspect of the device shown in Fig. 2(b) is that when the drain voltage of this component becomes larger than the source voltage, then the drain and source of the device will be exchanged and the bulk is connected to the source node. Therefore, the resistivity of the device will quickly switch from a very high value to a very low value similar to a PN junction. Depicted in Fig. 3, based on measurement results in 0.18  $\mu\text{m}$  CMOS, the device switches from subthreshold to strong inversion by changing the polarity of the source-drain voltage.

As far as the voltage swing across the resistor shown in 2(b) is less than 500 mV, the forward biased diode of the source-bulk junction draws very small amount of current and it has a negligible effect on the I/V characteristics, and power dissipation of the circuit.

### 2.2 Floating HVR

To compensate the asymmetric I/V characteristics of the simple devices discussed above, one can use two back-to-back equal-sized devices to implement a symmetric and floating pseudoresistor. The schematic of such a device is shown in Fig. 4.



**Fig. 4** Implementing floating HVR using two equal-sized back-to-back bulk-drain shorted PMOS devices.  $V_C = V_A - V_B$  can be adjusted for controlling the device resistivity

Regarding Fig. 4, since the two transistors in series are not linear devices,  $V_A \neq (V_{IN+} + V_{IN-})/2$ . Using the EKV model [16], it can be shown that:

$$V_A = V_0 - U_T \ln \left( \frac{\cosh \left( \frac{\Delta V}{2n_p U_T} (n_p - 1) \right)}{\cosh \frac{\Delta V}{2n_p U_T}} \right) \tag{4}$$

Therefore,  $V_A$  depends on input voltage swing,  $\Delta V$ . The voltage at node  $V_A$  exhibits a “V-shape” characteristic with respect to  $\Delta V$ . The minimum value occurs at  $\Delta V = 0$  V, and then increases by increasing  $|\Delta V|$ . Knowing the value of  $\Delta V$ , it is possible to calculate the current flow through MP1 and MP2:

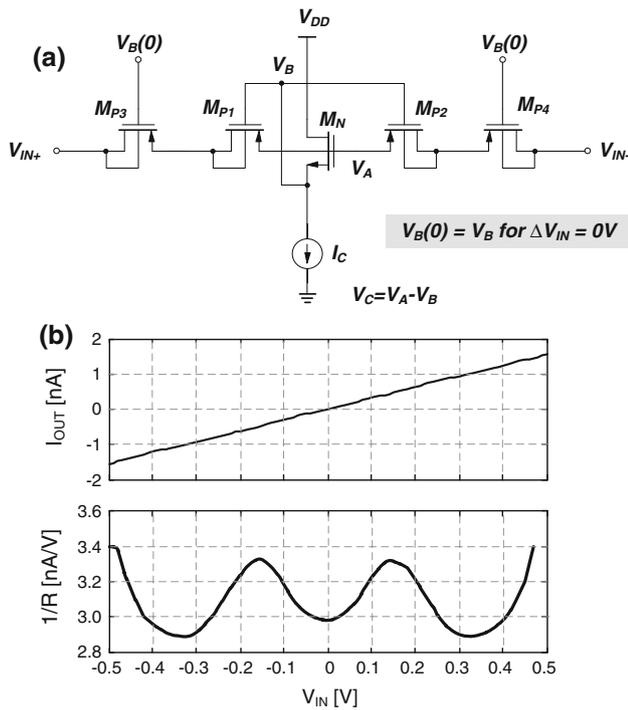
$$I_R = I_0 e^{\frac{V_0 - V_B}{n_p U_T}} e^{-\frac{\Delta V}{2n_p U_T}} \left( 1 - e^{\frac{\Delta V}{2U_T}} \cdot \frac{\cosh \frac{\Delta V}{2n_p U_T}}{\cosh \left( \frac{\Delta V}{2n_p U_T} (n_p - 1) \right)} \right) \tag{5}$$

Based on this, the circuit shown in Fig. 4 achieves its maximum resistivity when  $\Delta V = 0$  V, and then the resistivity drops when  $|\Delta V|$  increases. If we generate  $V_B$  from  $V_A$ , for example using a level shifter, then the linearity can be improved. The reason is that when  $V_A$  increases with increasing  $|\Delta V|$  as can be deduced from (4), the drop in resistivity will be canceled out partially by reduction of  $V_{SG}$  of the PMOS devices. In this case, the maximum value of the resistance will be no longer at  $|\Delta V| = 0$  V, but at two different points symmetrically placed with respect to the  $|\Delta V| = 0$  V.

Based on this discussion, it is possible to combine the two possible topologies to improve the linearity. For example, a series connection of the two circuits like the one shown in Fig. 5 could be used to significantly improve the linearity. In this circuit, MN has been used to generate the gate voltage of MP1–MP2,  $V_B$ , with respect to  $V_A$  as a level shifter circuit. Transistors MP1–MP2 are put in series to MP3–MP4 which are biased with a constant gate voltage. The resistivity of this circuit can be adjusted through the bias current of the level shifter circuit,  $I_C$ . By increasing this current, the source-gate voltage of MP1–MP2 increases, and hence the resistivity decreases. Based on simulation results shown in Fig. 5, the nonlinearity of this pseudoresistance is about 7% for 2 V peak-to-peak voltage swing. Using more transistors in series with appropriate gate bias voltages can provide HVRs with better linearity performance within a still compact area.

### 2.3 Extremely high-valued resistance

The analysis and discussion provided in Sect. 2.2 is based on the assumption that the devices are biased in inversion mode where  $V_{SG} \geq 0$ . If we reduce the gate source voltage



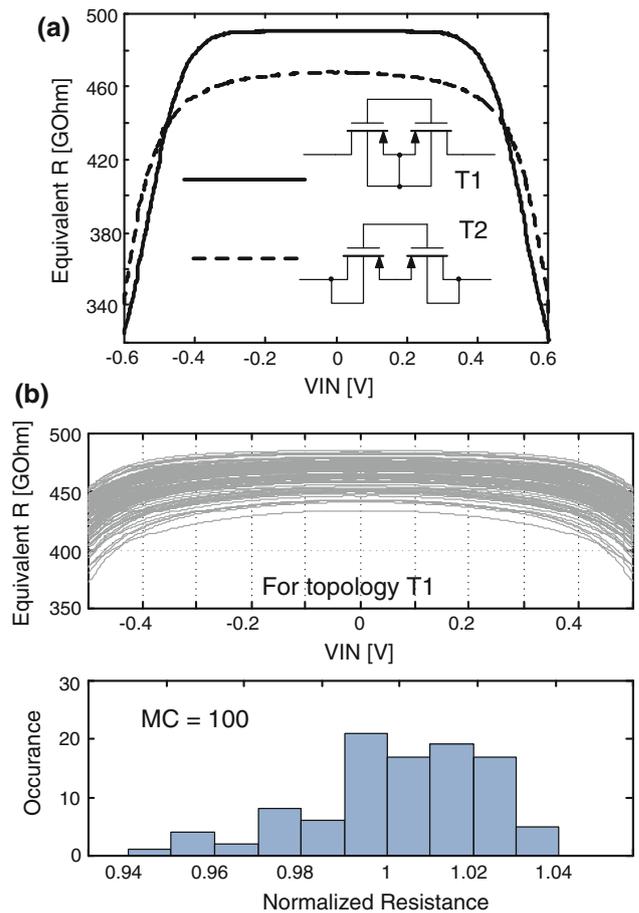
**Fig. 5** **a** Modified HVR with improved linearity performance. **b** Simulated I/V characteristics of the proposed HVR. This figure also shows the variation on absolute value of the HVR in different voltage drops

even further and make it negative, as shown in Fig. 6(a), it is possible to implement extremely high valued resistors with a fairly good linearity performance. This figure shows the resistivity of the circuit for two different configurations. Monte Carlo simulations have been performed to study the resistivity variation in this topology. As it is shown in Fig. 6(b), the resistivity variation based on MC = 100 simulations is only  $\sigma = 2.2\%$ . In the Monte Carlo simulation, mismatch and process variation for transistors is considered, while the supply voltage, temperature, and gate voltage of the devices are constant.

### 3 Tunable MOSFET-C filter design

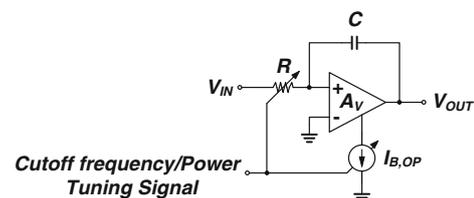
Using the HVR topology introduced in Sect. 2, it is possible to implement very low frequency MOSFET-C filters. Wide tuning range associated with this HVR is especially interesting for implementing a versatile filter that can be used in different applications.

Figure 7 proposes a first order MOSFET-C filter that uses a variable resistance for adjusting its cutoff frequency. Here, a widely tunable resistance and a high-gain and robust OTA (operational transconductance amplifier) with scalable power consumption are the main building blocks to implement a wide tuning range MOSFET-C filter. To



**Fig. 6** **a** Extremely high-valued compact resistor with a good linearity performance. The equivalent resistance of both topologies are shown. **b** Variation on resistivity based on Monte Carlo Simulations (MC = 100). The Monte Carlo simulations are shown for the topology T1. Here, supply voltage and temperature are constant and a fixed voltage is applied to the gate of transistors

scale the circuit power consumption with respect to the filter cutoff frequency ( $f_c$ ), it is necessary to change the power consumption of the amplifier (through  $I_{B,OP}$ ) proportional to  $f_c$  (or inversely proportional to  $R$ ). The circuit topologies introduced in Sect. 2 can be used to implement the required resistance in Fig. 7.



**Fig. 7** Tunable active-RC (MOSFET-C) filter using a variable resistor. The power consumption of the amplifier needs to be scalable with respect to the filter cutoff frequency

### 3.1 Amplifier design

In this work a two stage amplifier topology has been utilized. Assuming that the dominant pole is at the output of the first stage of amplifier, then the unity gain-bandwidth (UGBW) of the amplifier will be:

$$UGBW \simeq g_{m1}/(2\pi C_C) \tag{6}$$

which is proportional to  $g_{m1}$  (transconductance of the input stage shown in Fig. 8(a)), and inversely proportional to the compensation capacitance ( $C_C$ ). Assuming that the input devices are in subthreshold regime, then:

$$UGBW \simeq \frac{I_{SS}}{2nU_T} \cdot \frac{1}{2\pi C_C} \tag{7}$$

which is proportional to the bias current of the input stage of amplifier ( $I_{SS}$ ). Meanwhile, to have a phase margin of at least  $60^\circ$  [17]:

$$f_{p,nd} \geq 3 \times UGBW \tag{8}$$

where,  $f_{p,nd}$  is the non-dominant pole of the amplifier. The value of  $f_{p,nd}$  is inversely proportional to the load resistance

$R_L$ .  $R_L$  is the equivalent load resistance of the amplifier and as calculated in (1), it can be adjusted by the bias current. It is assumed that the output resistance of OTA itself is much larger than  $R_L$ .

As illustrated in Fig. 8(a), a two stage amplifier topology has been utilized for this purpose. To achieve a phase margin of at least  $60^\circ$ , based on (8) it is necessary to have:

$$\frac{1}{3} \cdot \frac{C_C}{C_L + C_C} \geq \frac{g_{m1}}{G_L} \tag{9}$$

Since the value of  $g_{m1}$  and  $G_L = 1/R_L$  are both proportional to the bias current, by properly choosing the size of devices, the right hand side of (9) can be made bias current independent. Therefore, as long as the devices are in subthreshold regime, the stability of the circuit can be guaranteed. In this figure,  $R_C$  is implemented using NMOS devices to follow the variations of the bias current. Figure 8(b) shows the simulated gain and phase margin of the proposed amplifier for different bias currents ranging over five orders of magnitude.

### 3.2 Dynamic range

The topology of the MOSFET-C filter shown in Fig. 7 is well suited for implementing constant dynamic range (DR) and widely adjustable filters. This property is mainly due to the almost constant *noise* and *linearity* performance of the filter over its tuning range. The total input referred noise power of the filter shown in Fig. 7 is:

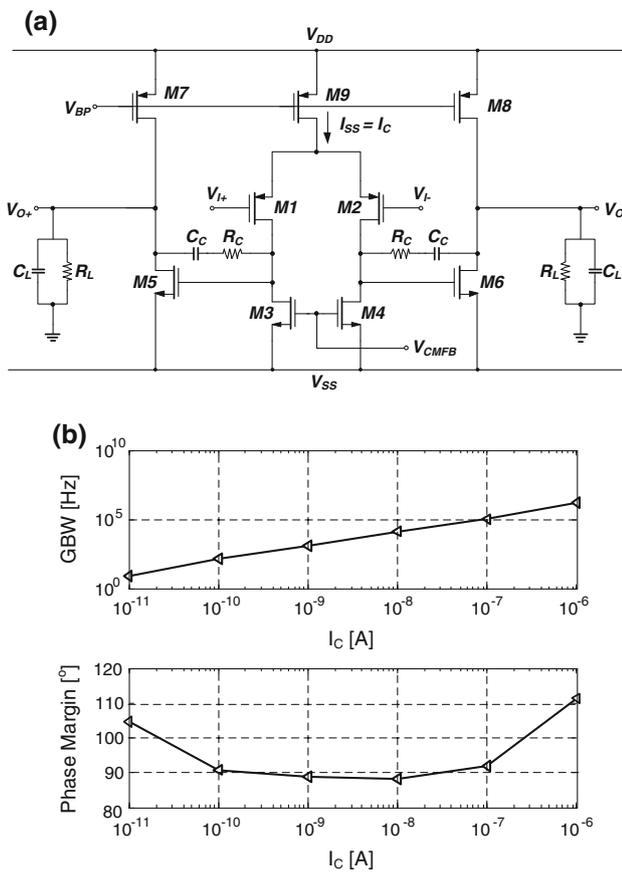
$$v_{n,in}^2 = \gamma_F \cdot (k \cdot T/C) \tag{10}$$

in which  $\gamma_F$  indicates the circuit excess noise factor and depends on the topology of the amplifier, resistances, as well as to the filter frequency transfer function (here,  $k$  is Boltzmann’s constant,  $T$  is the junction temperature in Kelvin, and  $C$  is the integration capacitance as shown in Fig. 7). Regarding (10) and assuming that  $\gamma_F$  is bias independent, then selecting a constant capacitor size results in constant total filter noise power for different cutoff frequencies.

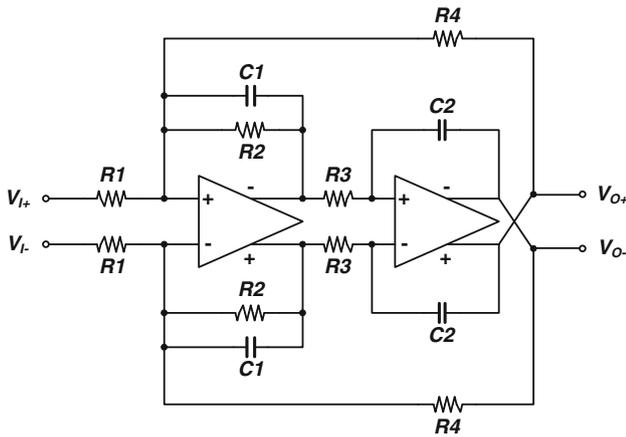
On the other hand, based on (2) the linearity of the resistance introduced in Fig. 4 is independent of the bias current or  $V_{SG}$  and the dependence on  $V_{SD}$  is the same for different resistor values. Hence, as long as the devices are in subthreshold regime, the linearity performance of the resistance remains unchanged, as well.

## 4 Experimental results

Using the proposed floating resistor topology shown in Fig. 5, a second order MOSFET-C filter has been implemented. The topology of the filter is illustrated in Fig. 9. In



**Fig. 8** a Circuit schematic of the amplifier. b Simulated unity gain bandwidth (UGBW) and phase margin of the amplifier for different current bias values. In this plot,  $I_C$  is the reference current value used to change the filter cutoff frequency ( $I_C = I_{SS}$ )



**Fig. 9** A second order MOSFET-C filter. All resistors are implemented using the proposed floating resistor topology shown in Fig. 4(a). Quality factor of this filter can be tuned through R2 independent to the cutoff frequency. In this design,  $R1 = R3 = R4$

this configuration, the cutoff frequency and the quality factor ( $Q$ ) of the filter can be tuned independently by adjusting the value of the appropriate resistors [10].

Simulations show that the cutoff frequency of the filter can be adjusted from 10 Hz to 200 kHz. The linearity performance of the filter remains almost constant as long as the devices are in subthreshold. For high bias currents, when the devices are entering into medium and strong inversion, linearity improves slightly. For low input frequencies ( $f_{in} \ll f_c$ ), the circuit transfer characteristic depends only on the ratio of resistors. Therefore, the nonlinearity of the resistors is not significant as long as they are well matched. For higher frequencies, when both capacitors and resistors are participating in constructing the output signal, then the nonlinearity of the resistors become important.

The chip photomicrograph of the filter is shown in Fig. 10. The proposed filter occupies a silicon area of

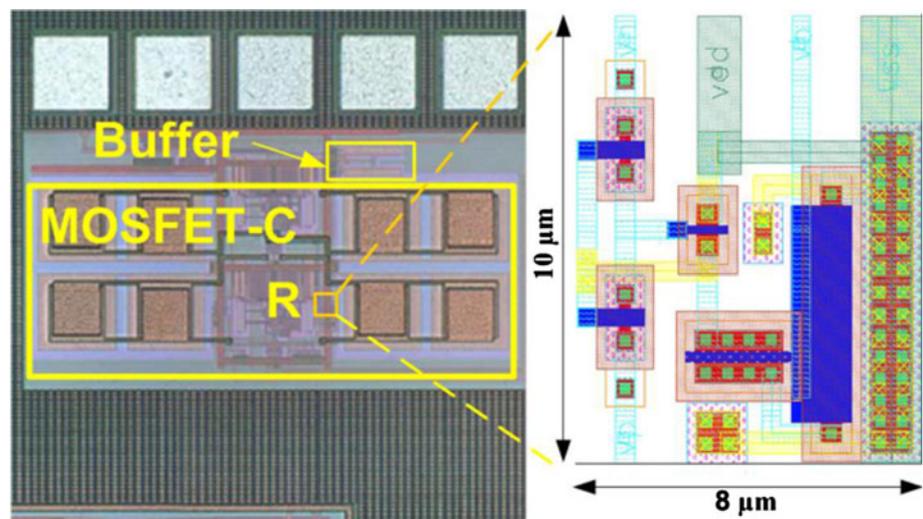
$420 \mu\text{m} \times 210 \mu\text{m}$  while using MiM capacitors. As shown in Fig. 10, the area of the proposed floating resistors can be compared with the size of other components in the circuit.

#### 4.1 Frequency response

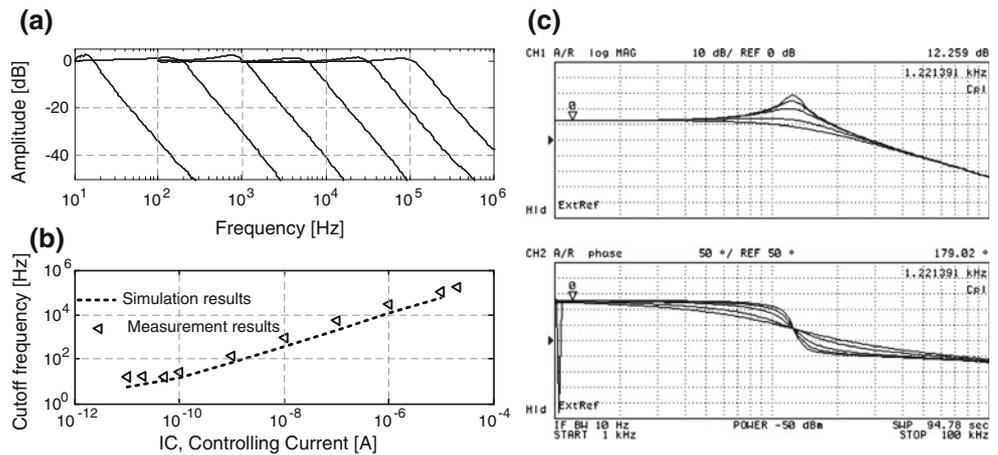
The measured frequency response of the filter versus input frequency controlling current ( $I_C$ ) is shown in Fig. 11(a). In this measurement, the bias current of all the resistors as well as the bias current of amplifiers are scaling with respect to  $I_C$ . Depicted in this figure, the controlling current can be as low as  $I_C = 100 \text{ pA}$  for  $f_c \approx 20 \text{ Hz}$ . This low cutoff frequency has been achieved using 2 pF filter capacitors. As a result, this topology shows to be very suitable for implementing very low frequency filters, using limited silicon area.

Figure 11(b) demonstrates the tunability of this filter in comparison to the simulation results. The measured cutoff frequency of the filter is  $f_c = 20 \text{ Hz} - 184 \text{ kHz}$  which is slightly less than five decades. This very wide tuning range corresponds to the adjustability range of the proposed floating resistor which is shown in Fig. 12 based on measurement results. The measured frequency response shows a very good agreement with the simulation results. The small difference that can be seen between measurement and simulation results which is a relatively constant ratio over the entire range is mainly due to the difference between the capacitor values in the simulations and measurements. The difference between measurements and simulation results becomes more evident (about 50%) in very low cutoff frequencies mainly because of difficulty of precisely adjusting the controlling current. An internal current divider circuit has been employed to divide and external controlling current and produce the controlling current of the filter which loses its precision below 100 pA.

**Fig. 10** Chip photomicrograph of the filter implemented with 0.18  $\mu\text{m}$  CMOS technology (inset: implementation of the floating tunable resistors)



**Fig. 11** Measured MOSFET-C filter characteristics: **a** frequency transfer characteristics. **b** cutoff frequency versus tuning current in comparison to the simulation results. **c** Q tuning by changing R2 value value at  $I_C = 1$  nA



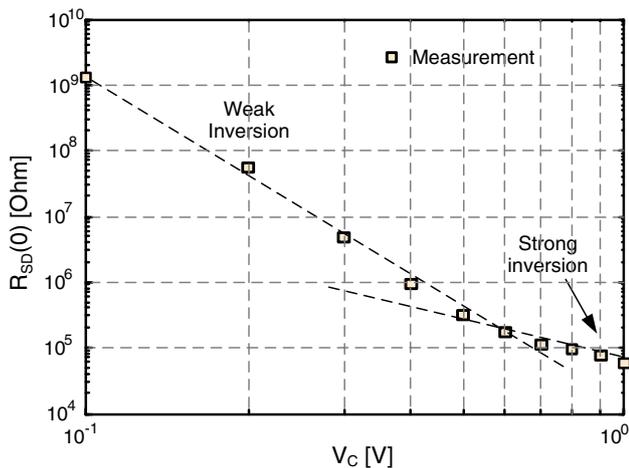
The normalized power consumption of the proposed second order filter is 1,080 pW/Hz.

Depicted in Fig. 11(c), it is possible to adjust the  $Q$  of the filter independent to the cutoff frequency through changing R2 in Fig. 9. Measured output phase of the proposed second order MOSFET-C filter shows that there is negligible variation on filter cutoff frequency when the quality factor of the filter is changing. On the other hand, based on Fig. 11(a) changing the cutoff frequency does not change the quality factor of the filter.

As shown in [18] and [19], an on-chip phase-locked loop (PLL) based tuning system will be employed in the final design to control the bandwidth of the filter. Figure 12 illustrated the tunability of the HVR based on experimental data. The tunability of the HVR corresponds to the tunability of the filter as shown in Fig. 11.

#### 4.2 Dynamic range

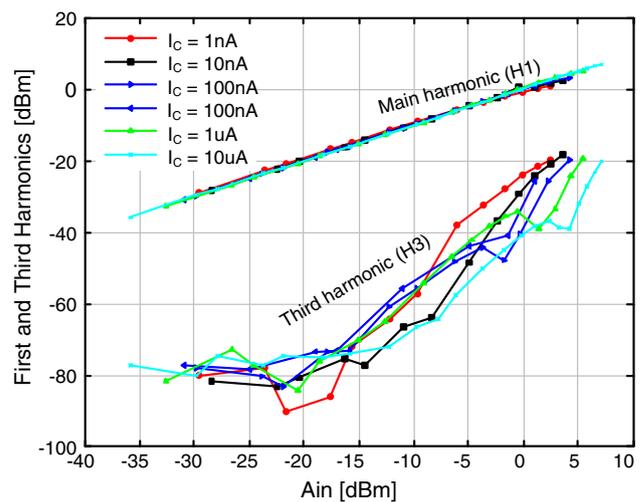
Figure 13 shows the measured third harmonic distortion ( $HD3 = H1/H3$ ) of the filter at different cutoff frequencies



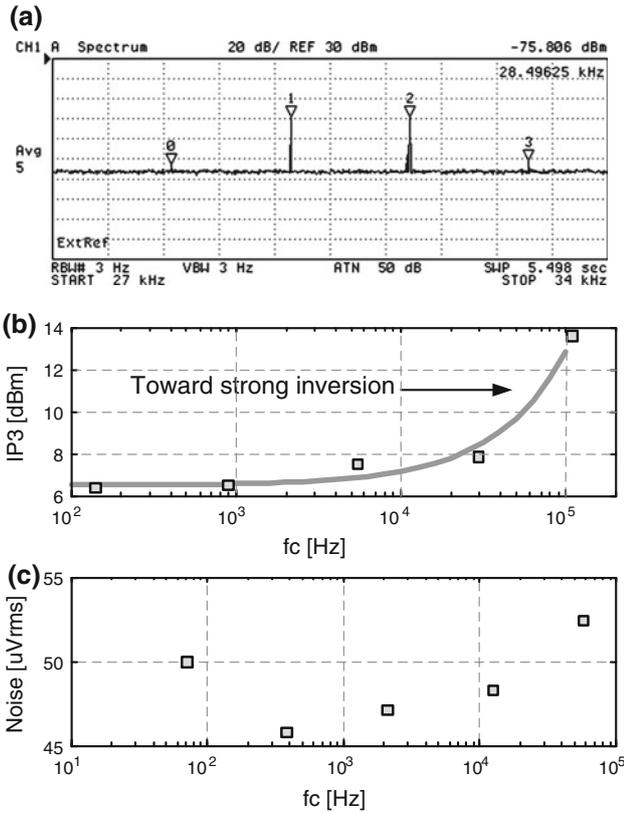
**Fig. 12** Measured absolute value of the proposed floating resistance in different source-gate voltage values

versus input signal amplitude. The cutoff frequency of the filter is adjusted with changing the controlling current as  $I_C = 1$  nA to 10  $\mu$ A. For each cutoff frequency, the input voltage swing is swept from  $-35$  to 5 dBm. In each measurement, the frequency of the input signal has been selected to be four times smaller than the cutoff frequency of the filter. As can be seen, the linearity performance of the filter remains almost unchanged for the entire tuning range where the difference of the first and the third harmonics ( $H1/H3$ ) are approximately 60 dB, and it can be maintained over four decades, for  $A_{in} = -20$  dB (as the gain of filter is one,  $A_{out} = -20$  dB).

The measured input referred third intercept point (IIP3) and noise of this filter are shown in Fig. 14(a)–(c). By changing the controlling current,  $I_C$ , the cutoff frequency has been changed, and in each point noise and IIP3 of the filter are measured. As expected, the total noise power remains fairly constant over the entire tuning range. The total integrated noise for this filter is in the range of



**Fig. 13** Measured third harmonic for different cutoff frequencies. Cutoff frequency has been adjusted through controlling current,  $I_C$ . Here, the reference voltage is 50  $\Omega$



**Fig. 14** Measured results: **a** spectrum of the output signal, **b** third order intermodulation intercept point, and **c** noise, of the proposed MOSFET-C filter. Here, the reference voltage is 50 Ω

45–55 μV<sub>rms</sub> when the cutoff frequency is changing from about 80 Hz to 184 kHz.

Meanwhile, as long as the devices in the proposed floating resistors are in subthreshold regime, the filter exhibits a constant IIP3. When the devices enter into strong inversion, IIP3 improves by increasing the controlling current. This behavior can be seen in measurements as depicted in Fig. 14(b). The IIP3 of the filter is slightly less than 8 dBm for low cutoff frequencies and starts to increase for frequencies above 10 kHz and finally reaches to 14 dBm for  $f_c = 100$  kHz.

### 4.3 Comparison and figure of merit

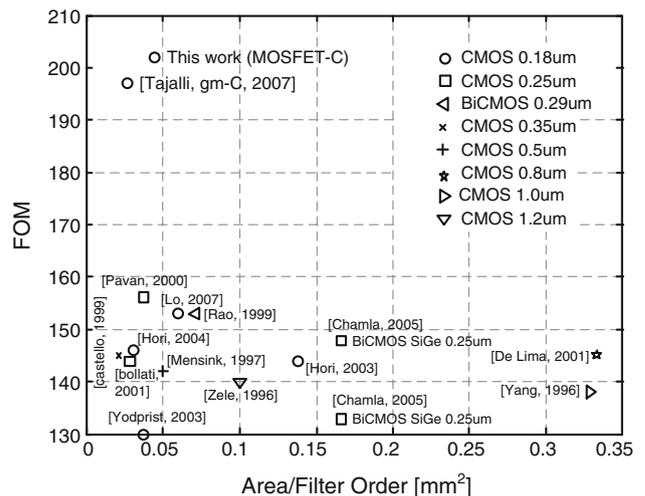
Table 1 summarizes the specifications of the filter. This filter consumes 540 pW/Hz/pole and occupies 0.045 mm<sup>2</sup>/pole area. As the comparison in Table 1 shows, using high-valued resistors and avoiding less power efficient techniques such as transconductance scaling, or current division [1, 2, 20, 21] has resulted in much less normalized power dissipation. The figure of merit (FoM) that is achieved based on this definition [22]:

**Table 1** Specifications of the proposed filter in comparison to some other works

Parameter	This work	[1]	[2]
$V_{DD}$ (V)	1.8	±1.5	±1.5
Technology	0.18 μm	0.8 μm	0.8 μm
Order	2	6	1
$f_{c,min}$ (Hz)	20	2.4	0.016
$f_{c,Max}$ (Hz)	184 k		0.8
$f_{c,Max}/f_{c,min}$ (Hz/Hz)	9,200		50
Normalized $P_{diss}$ (pW/Hz/pole)	540	$694 \times 10^3$	$287 \times 10^3$
Area (mm <sup>2</sup> )	0.09	1	0.1
Normalized area (mm <sup>2</sup> /pole)	0.045	0.17	0.1
Noise (μV <sub>rms</sub> )	50		50
IIP3 (dBm)	9		
IMFDR (dB)	70		
FOM	202		

$$FOM = 10 \log \left( \frac{IMFDR_{lin.} \times \Gamma_f}{P_{diss}/(N \times f_c)} \right) \quad (11)$$

is 202. Here,  $IMFDR_{lin.}$  stands for intermodulation free dynamic range, and  $\Gamma_f$  indicates the ratio of the maximum to minimum filter cutoff frequencies. Figure 15 compares the figure of merit of this filter with some other already published reports [22–39]. The improvement observed for this design is mainly due to the simple topologies that have been used to implement the circuits. This approach also results in a very area and power efficient filter. As the comparison in Table 1 shows, using high-valued resistors and avoiding less power efficient techniques such as transconductance scaling, or current division has resulted in much higher power efficiency.



**Fig. 15** FOM comparison to some other reports versus normalized filter area (area is normalized to the order of each filter). The data points used in this figure are extracted from [22–39]

## 5 Conclusions

Novel circuit techniques for implementing very high-valued and compact pseudoresistors ranging from few hundreds of  $M\Omega$  to few hundreds of  $G\Omega$ , have been introduced and analyzed. Using the proposed high-value resistance, a very low frequency and power-efficient MOSFET-C filter has been implemented. Consuming 540 pW/Hz/pole, the power dissipation of this filter changes linearly with the cutoff frequency of the filter which can be tuned over 20 Hz–184 kHz. Very low power dissipation, and small area occupation ( $0.045 \text{ mm}^2/\text{pole}$ ), as well as simple design process, make this filter very suitable for implantable, battery-less biomedical applications.

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